

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, May 19, 2012 03:46 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FS6S1265REYDTU	FS6S1265REYDTU	TO-3PF-5			INTERNAL SUZHOU	5.841	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom
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RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted
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Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC
 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name TO-3PF-5

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	11.200	Supplier		Silicon	11.200	7440-21-3	1917
Die Attach	Other Nonferrous metals & alloys	11.200	A	Lead/Lead Compounds	Lead	9.856	7439-92-1	1687
			Supplier		Silver	0.224	7440-22-4	38
			Supplier		Tin	1.120	7440-31-5	192
Die Attach Tape	Other Plastics & Rubber	0.224	Supplier		Aminophenoxy Benzene	0.083	2479-46-1	14
			Supplier		Benzophenone Tetracarboxylic Dianhydride	0.056	2421-28-5	10
			Supplier		PBTA	0.085	trade secret	15
Encapsulation	Thermoplastics	2969.700	B	Antimony/Antimony Compounds	Antimony Trioxide	74.300	1309-64-4	12720
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	89.100	6386-73-8	15254
			Supplier		Carbon Black	22.300	1333-86-4	3818
			Supplier		Epoxy Resin	594.000	29690-82-2	101695
			Supplier		Silica, vitreous	2190.000	60676-86-0	374935
Lead Frame	Other Ferrous alloys, non-stainless steels	2810.493	Supplier		Copper	2800.000	7440-50-8	479369
			Supplier		Iron	2.810	7439-89-6	481
			Supplier		Phosphorus	0.843	7723-14-0	144
			Supplier		Silver	6.840	7440-22-4	1171
Plating	Other Nonferrous metals & alloys	37.000	Supplier		Tin	37.000	7440-31-5	6335
Wire Bond	Precious metals	1.200	Supplier		Gold	1.200	7440-57-5	205